



# SOT1202

**XSON6: extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm**

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	XSON6
<b>Package type industry code</b>	XSON6
<b>Package style descriptive code</b>	XSON (extremely thin small outline; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	6-4-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.95	-	1	1.05	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	[tbd]	-	[tbd]	0.35	mm
A <sub>2</sub>	package height	[tbd]	-	[tbd]	0.31	mm
e	nominal pitch	-	-	0.55	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	6	-	

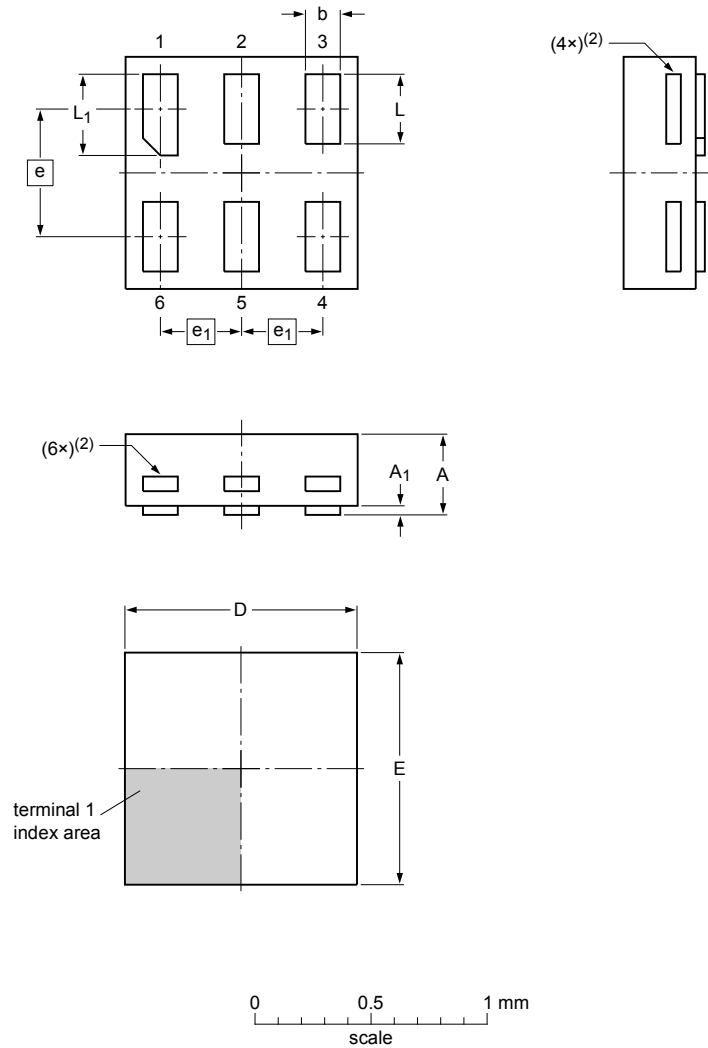


XSON6: extremely thin small outline package; no leads; 6 terminals; 6 terminals; body 1.0 x 1.0 x 0.35 mm

## 2. Package outline

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SOT1202



Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max 0.35	0.04	0.20	1.05	1.05			0.35	0.40
	nom 0.15		1.00	1.00	0.55	0.35	0.30	0.35	
	min 0.12		0.95	0.95				0.27	0.32

Note

1. Including plating thickness.
2. Visible depending upon used manufacturing technology.

sot1202\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1202					10-04-02 10-04-06

Fig. 1. Package outline XSON6 (SOT1202)

XSON6: extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm

### 3. Soldering

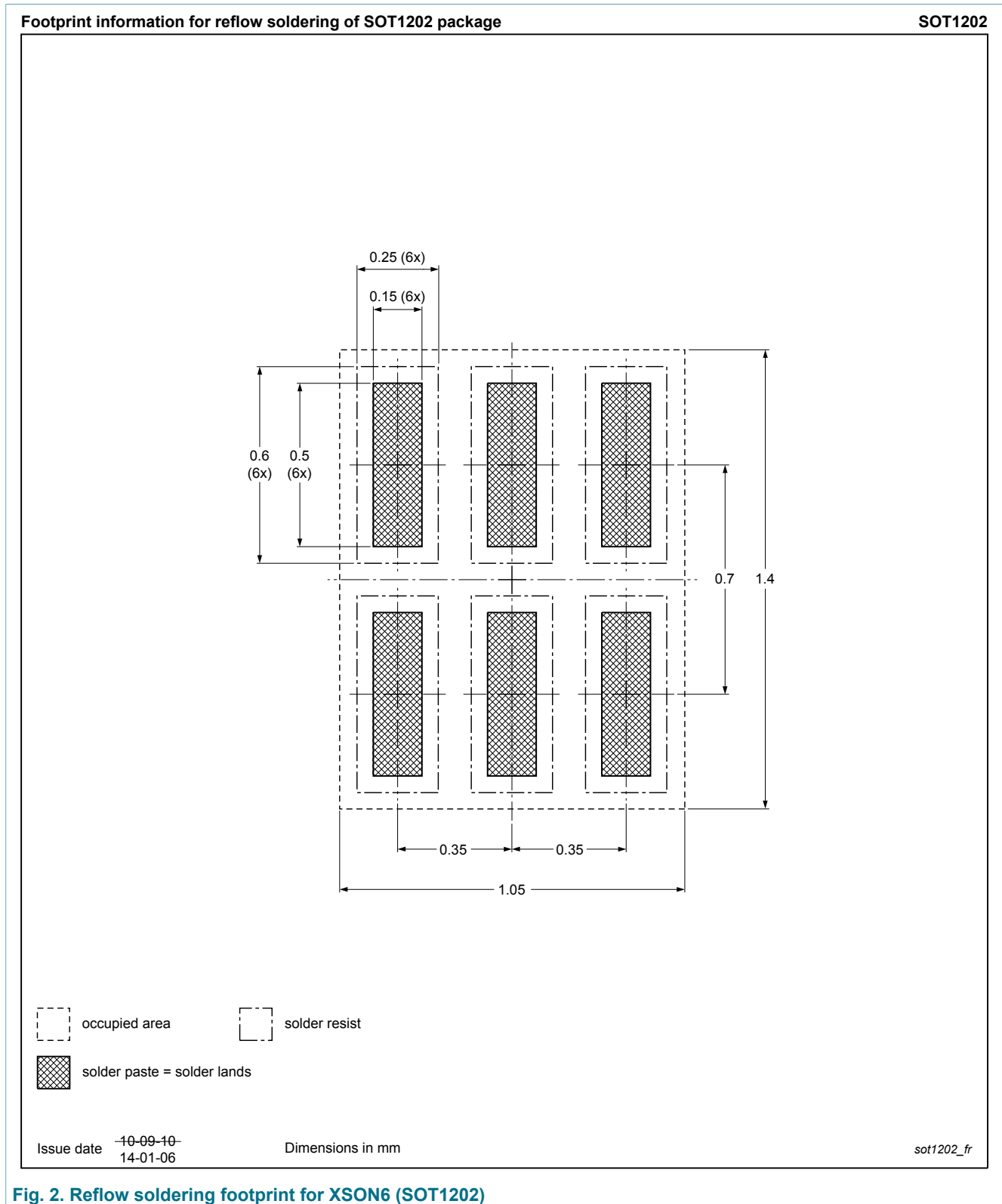


Fig. 2. Reflow soldering footprint for XSON6 (SOT1202)

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## 4. Legal information

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## 5. Contents

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1. Package summary.....	1
2. Package outline.....	2
3. Soldering.....	3
4. Legal information.....	4

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